



April 2015

## 4N25M, 4N26M, 4N27M, 4N28M, 4N35M, 4N36M, 4N37M 6-Pin General Purpose Phototransistor Optocouplers

### Features

- Minimum Current Transfer Ratio at  $I_F = 10 \text{ mA}$ ,  $V_{CE} = 10 \text{ V}$ :
  - 10% for 4N27M and 4N28M
  - 20% for 4N25M and 4N26M
  - 100% for 4N35M, 4N36M and 4N37M
- Safety and Regulatory Approvals:
  - UL1577, 4,170  $V_{AC_{RMS}}$  for 1 Minute
  - DIN-EN/IEC60747-5-5, 850 V Peak Working Insulation Voltage

### Description

The general purpose optocouplers consist of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a standard plastic six-pin dual-in-line package.

### Applications

- Power Supply Regulators
- Digital Logic Inputs
- Microprocessor Inputs

### Schematic



- PIN 1. ANODE  
2. CATHODE  
3. NO CONNECTION  
4. EMITTER  
5. COLLECTOR  
6. BASE

Figure 1. Schematic

### Package Outlines

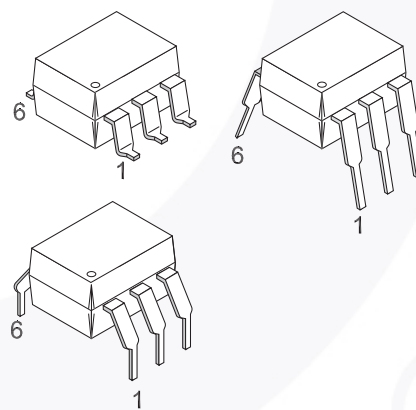


Figure 2. Package Outlines

## Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

Parameter		Characteristics
Installation Classifications per DIN VDE 0110/1.89 Table 1, For Rated Mains Voltage	< 150 V <sub>RMS</sub>	I–IV
	< 300 V <sub>RMS</sub>	I–IV
Climatic Classification		55/100/21
Pollution Degree (DIN VDE 0110/1.89)		2
Comparative Tracking Index		175

Symbol	Parameter	Value	Unit
V <sub>PR</sub>	Input-to-Output Test Voltage, Method A, V <sub>IORM</sub> × 1.6 = V <sub>PR</sub> , Type and Sample Test with t <sub>m</sub> = 10 s, Partial Discharge < 5 pC	1360	V <sub>peak</sub>
	Input-to-Output Test Voltage, Method B, V <sub>IORM</sub> × 1.875 = V <sub>PR</sub> , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC	1594	V <sub>peak</sub>
V <sub>IORM</sub>	Maximum Working Insulation Voltage	850	V <sub>peak</sub>
V <sub>IOTM</sub>	Highest Allowable Over-Voltage	6000	V <sub>peak</sub>
	External Creepage	≥ 7	mm
	External Clearance	≥ 7	mm
	External Clearance (for Option TV, 0.4" Lead Spacing)	≥ 10	mm
DTI	Distance Through Insulation (Insulation Thickness)	≥ 0.5	mm
T <sub>S</sub>	Case Temperature <sup>(1)</sup>	175	°C
I <sub>S,INPUT</sub>	Input Current <sup>(1)</sup>	350	mA
P <sub>S,OUTPUT</sub>	Output Power <sup>(1)</sup>	800	mW
R <sub>IO</sub>	Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V <sup>(1)</sup>	> 10 <sup>9</sup>	Ω

### Note:

1. Safety limit values – maximum values allowed in the event of a failure.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Value	Unit
<b>TOTAL DEVICE</b>			
$T_{STG}$	Storage Temperature	-40 to +125	$^\circ\text{C}$
$T_{OPR}$	Operating Temperature	-40 to +100	$^\circ\text{C}$
$T_J$	Junction Temperature	-40 to +125	$^\circ\text{C}$
$T_{SOL}$	Lead Solder Temperature	260 for 10 seconds	$^\circ\text{C}$
$P_D$	Total Device Power Dissipation @ $T_A = 25^\circ\text{C}$	270	mW
	Derate Above $25^\circ\text{C}$	2.94	mW/ $^\circ\text{C}$
<b>EMITTER</b>			
$I_F$	DC/Average Forward Input Current	60	mA
$V_R$	Reverse Input Voltage	6	V
$I_F(\text{pk})$	Forward Current – Peak (300 $\mu\text{s}$ , 2% Duty Cycle)	3	A
$P_D$	LED Power Dissipation @ $T_A = 25^\circ\text{C}$	120	mW
	Derate Above $25^\circ\text{C}$	1.41	mW/ $^\circ\text{C}$
<b>DETECTOR</b>			
$V_{CEO}$	Collector-to-Emitter Voltage	30	V
$V_{CBO}$	Collector-to-Base Voltage	70	V
$V_{ECO}$	Emitter-to-Collector Voltage	7	V
$P_D$	Detector Power Dissipation @ $T_A = 25^\circ\text{C}$	150	mW
	Derate Above $25^\circ\text{C}$	1.76	mW/ $^\circ\text{C}$

## Electrical Characteristics

TA = 25°C unless otherwise specified.

### Individual Component Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>EMITTER</b>						
V <sub>F</sub>	Input Forward Voltage	I <sub>F</sub> = 10 mA		1.18	1.50	V
I <sub>R</sub>	Reverse Leakage Current	V <sub>R</sub> = 6.0 V		0.001	10	μA
<b>DETECTOR</b>						
BV <sub>CEO</sub>	Collector-to-Emitter Breakdown Voltage	I <sub>C</sub> = 1.0 mA, I <sub>F</sub> = 0	30	100		V
BV <sub>CBO</sub>	Collector-to-Base Breakdown Voltage	I <sub>C</sub> = 100 μA, I <sub>F</sub> = 0	70	120		V
BV <sub>ECO</sub>	Emitter-to-Collector Breakdown Voltage	I <sub>E</sub> = 100 μA, I <sub>F</sub> = 0	7	10		V
I <sub>CEO</sub>	Collector-to-Emitter Dark Current	V <sub>CE</sub> = 10 V, I <sub>F</sub> = 0		1	50	nA
I <sub>CBO</sub>	Collector-to-Base Dark Current	V <sub>CB</sub> = 10 V			20	nA
C <sub>CE</sub>	Capacitance	V <sub>CE</sub> = 0 V, f = 1 MHz		8		pF

### Transfer Characteristics

Symbol	Parameter	Test Conditions	Device	Min.	Typ.	Max.	Unit
<b>DC CHARACTERISTICS</b>							
CTR	Current Transfer Ratio, Collector-to-Emitter	I <sub>F</sub> = 10 mA, V <sub>CE</sub> = 10 V	4N35M, 4N36M, 4N37M	100			%
			4N25M, 4N26M	20			%
			4N27M, 4N28M	10			%
		I <sub>F</sub> = 10 mA, V <sub>CE</sub> = 10 V, T <sub>A</sub> = -55°C	4N35M, 4N36M, 4N37M	40			%
I <sub>F</sub> = 10 mA, V <sub>CE</sub> = 10 V, T <sub>A</sub> = +100°C	4N35M, 4N36M, 4N37M	40			%		
V <sub>CE (SAT)</sub>	Collector-to-Emitter Saturation Voltage	I <sub>C</sub> = 2 mA, I <sub>F</sub> = 50 mA	4N25M, 4N26M, 4N27M, 4N28M			0.5	V
		I <sub>C</sub> = 0.5 mA, I <sub>F</sub> = 10 mA	4N35M, 4N36M, 4N37M			0.3	V
<b>AC CHARACTERISTICS</b>							
T <sub>ON</sub>	Non-Saturated Turn-on Time	I <sub>F</sub> = 10 mA, V <sub>CC</sub> = 10 V, R <sub>L</sub> = 100 Ω (Figure 13)	4N25M, 4N26M, 4N27M, 4N28M		2		μs
		I <sub>C</sub> = 2 mA, V <sub>CC</sub> = 10 V, R <sub>L</sub> = 100 Ω (Figure 13)	4N35M, 4N36M, 4N37M		2	10	μs
T <sub>OFF</sub>	Turn-off Time	I <sub>F</sub> = 10 mA, V <sub>CC</sub> = 10 V, R <sub>L</sub> = 100 Ω (Figure 13)	4N25M, 4N26M, 4N27M, 4N28M		2		μs
		I <sub>C</sub> = 2 mA, V <sub>CC</sub> = 10 V, R <sub>L</sub> = 100 Ω (Figure 13)	4N35M, 4N36M, 4N37M		2	10	μs

### Isolation Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>ISO</sub>	Input-Output Isolation Voltage	t = 1 Minute	4170			V <sub>AC RMS</sub>
C <sub>ISO</sub>	Isolation Capacitance	V <sub>I-O</sub> = 0 V, f = 1 MHz		0.2		pF
R <sub>ISO</sub>	Isolation Resistance	V <sub>I-O</sub> = ±500 VDC, T <sub>A</sub> = 25°C	10 <sup>11</sup>			Ω

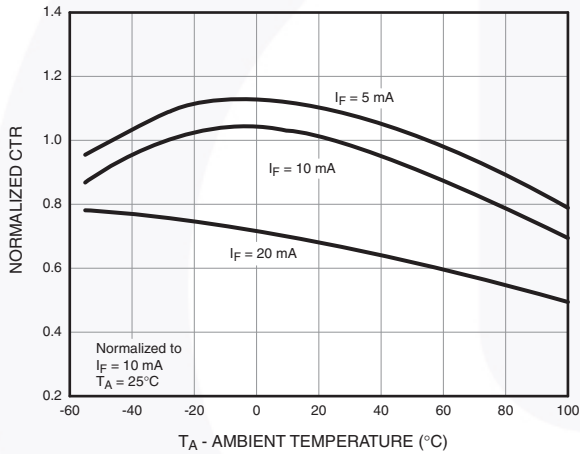
### Typical Performance Curves



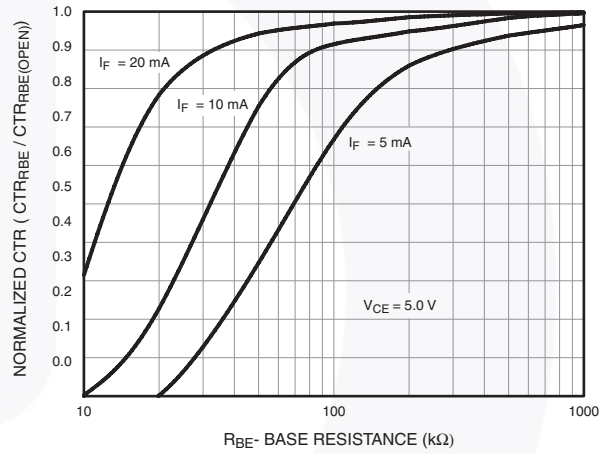
**Figure 3. LED Forward Voltage vs. Forward Current**



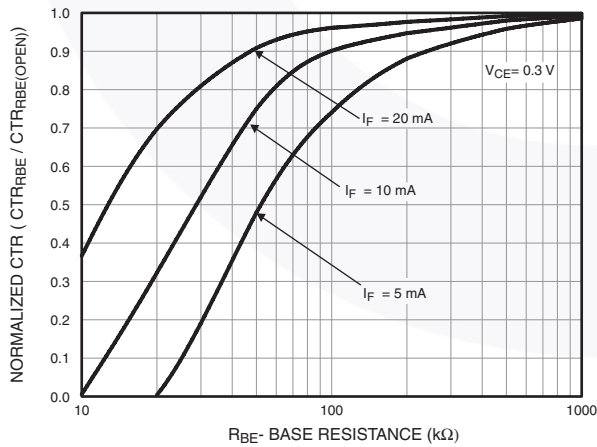
**Figure 4. Normalized CTR vs. Forward Current**



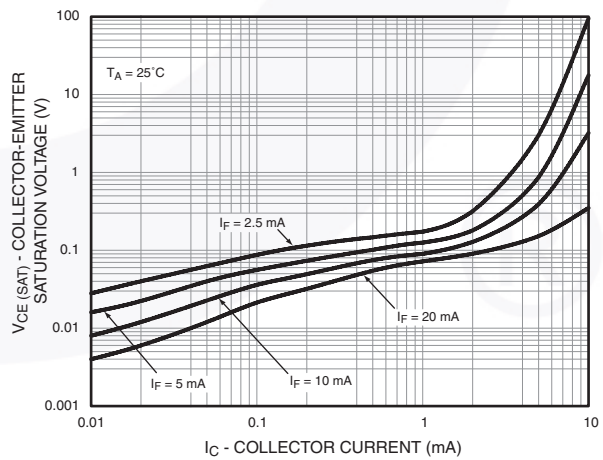
**Figure 5. Normalized CTR vs. Ambient Temperature**



**Figure 6. CTR vs. R<sub>BE</sub> (Unsaturated)**



**Figure 7. CTR vs. R<sub>BE</sub> (Saturated)**



**Figure 8. Collector-Emitter Saturation Voltage vs. Collector Current**

### Typical Performance Curves (Continued)



Figure 9. Switching Speed vs. Load Resistor



Figure 10. Normalized  $t_{on}$  vs.  $R_{BE}$



Figure 11. Normalized  $t_{off}$  vs.  $R_{BE}$



Figure 12. Dark Current vs. Ambient Temperature

### Switching Time Test Circuit and Waveforms



Figure 13. Switching Time Test Circuit and Waveforms

### Reflow Profile



Figure 14. Reflow Profile

## Ordering Information

Part Number	Package	Packing Method
4N25M	DIP 6-Pin	Tube (50 Units)
4N25SM	SMT 6-Pin (Lead Bend)	Tube (50 Units)
4N25SR2M	SMT 6-Pin (Lead Bend)	Tape and Reel (1000 Units)
4N25VM	DIP 6-Pin, DIN EN/IEC60747-5-5 Option	Tube (50 Units)
4N25SVM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tube (50 Units)
4N25SR2VM	SMT 6-Pin (Lead Bend), DIN EN/IEC60747-5-5 Option	Tape and Reel (1000 Units)
4N25TVM	DIP 6-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 Option	Tube (50 Units)

**Note:**

2. The product orderable part number system listed in this table also applies to the 4N26M, 4N27M, 4N28M, 4N35M, 4N36M, and 4N37M devices.

## Marking Information



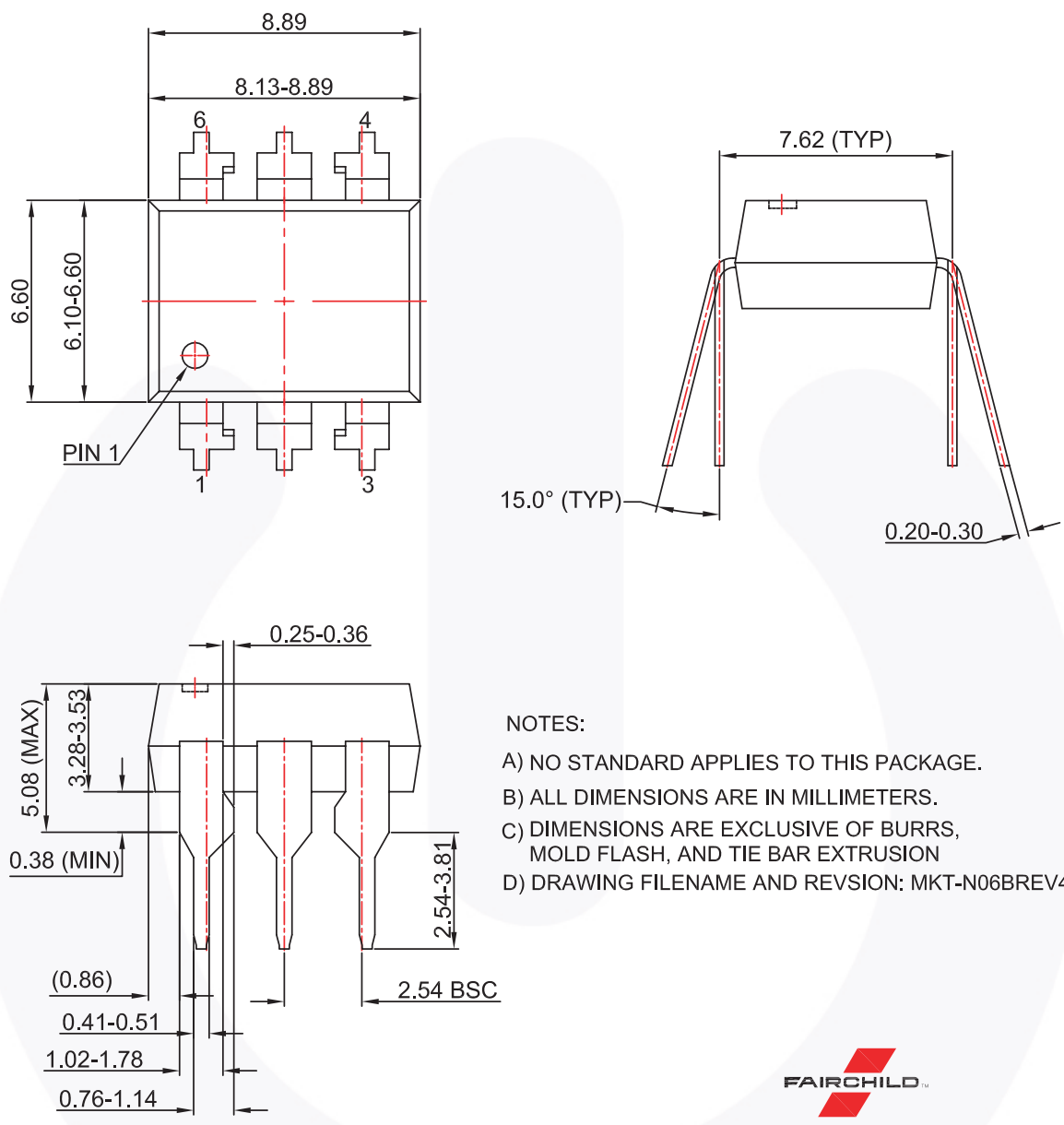
Figure 15. Top Mark

Table 1. Top Mark Definitions

1	Fairchild Logo
2	Device Number
3	DIN EN/IEC60747-5-5 Option (only appears on component ordered with this option)
4	One-Digit Year Code, e.g., "5"
5	Digit Work Week, Ranging from "01" to "53"
6	Assembly Package Code



**Package Dimensions**

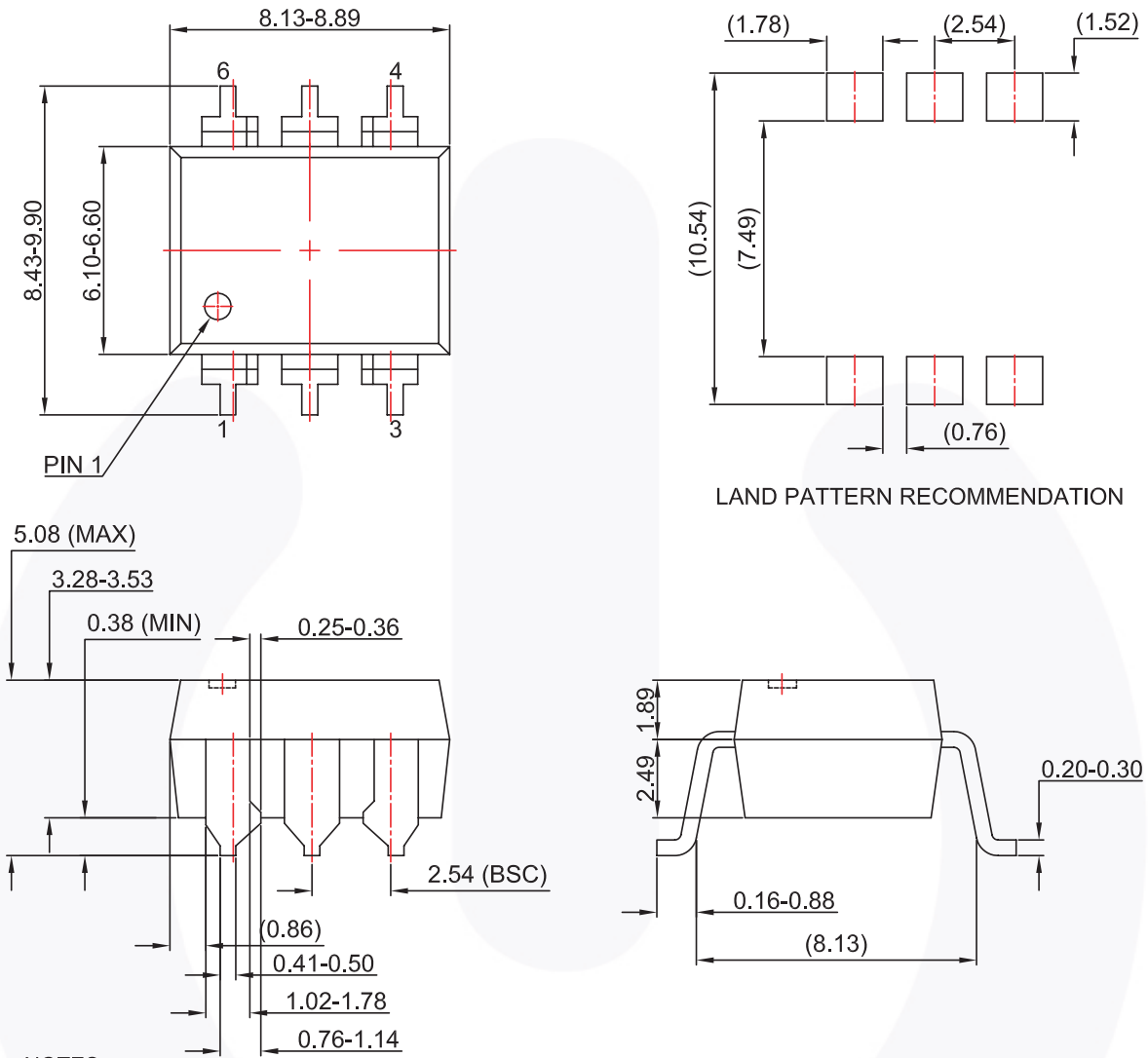


- NOTES:
- A) NO STANDARD APPLIES TO THIS PACKAGE.
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
  - D) DRAWING FILENAME AND REVISION: MKT-N06BREV4.



**Figure 16. 6-pin DIP Through Hole**

Package Dimensions (Continued)



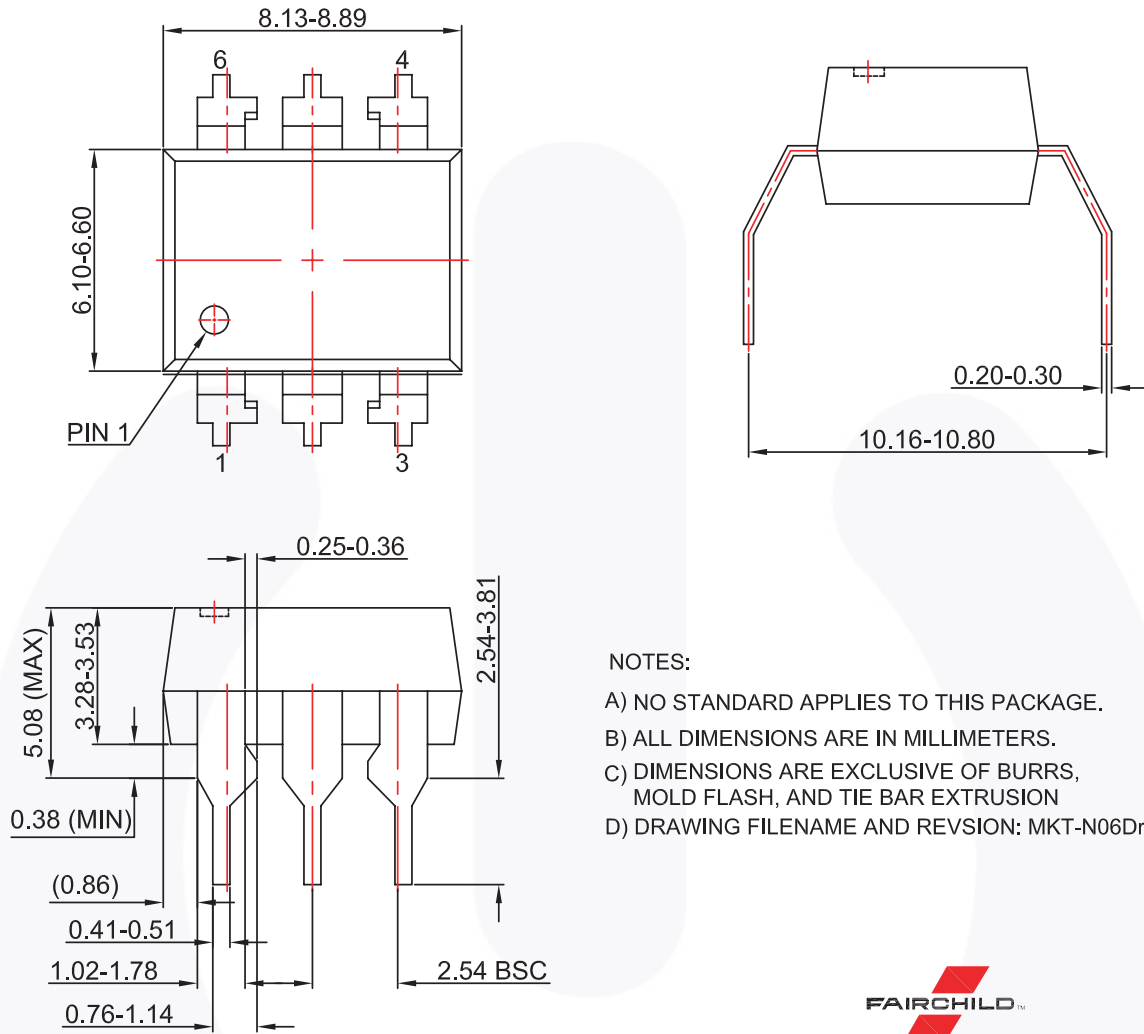
NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
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Figure 17. 6-pin DIP Surface Mount

Package Dimensions (Continued)



NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N06Drev4








Figure 18. 6-pin DIP 0.4" Lead Spacing



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